

**DECLARATION AND POWER OF ATTORNEY FOR U.S. PATENT APPLICATION**

( ) Original ( ) Supplemental ( ) Substitute (v) PCT ( ) Design

As a below named inventor, I hereby declare that: my residence, post office address and citizenship are as stated below next to my name; that I verily believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural inventors are named below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

Title: Semiconductor Device Package Manufacturing Method and  
Semiconductor Device Package Manufactured by the Method

of which is described and claimed in:

- ( ) the attached specification, or  
 ( ) the specification in the application Serial No. \_\_\_\_\_ filed \_\_\_\_\_;  
 and with amendments through \_\_\_\_\_ (if applicable), or  
 (v) the specification in International Application No. PCT/ JP00/04699, filed July 13, 2000, and as amended  
 on \_\_\_\_\_ (if applicable).

I hereby state that I have reviewed and understand the content of the above-identified specification, including the claims, as amended by any amendment(s) referred to above.

I acknowledge my duty to disclose to the Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, §1.56.

I hereby claim priority benefits under Title 35, United States Code, §119 (and §172 if this application is for a Design) of any application(s) for patent or inventor's certificate listed below and have also identified below any application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

COUNTRY	APPLICATION NO.	DATE OF FILING	PRIORITY CLAIMED
Japan	11-202847	July 16, 1999	YES
Japan	2000-63686	March 8, 2000	YES

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose information material to patentability as defined in Title 37, Code of Federal Regulations, §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application.

APPLICATION SERIAL NO.	U.S. FILING DATE	STATUS: PATENTED, PENDING, ABANDONED

4 And I hereby appoint John T. Miller, Reg. No. 21,120; Michael R. Davis, Reg. No. 25,134; ~~Matthew M. Jacob, Reg. No. 25,154;~~ Jeffrey Noltan, Reg. No. 25,408; Warren M. Cheek, Jr., Reg. No. 33,367; Nils E. Pedersen, Reg. No. 33,145 and Charles R. Watts, Reg. No. 33,142, who together constitute the firm of WENDEROTH, LIND & PONACK, L.L.P., attorneys to prosecute this application and to transact all business in the U.S. Patent and Trademark Office connected therewith.

I hereby authorize the U.S. attorneys named herein to accept and follow instructions from Aoyama & Partners as to any action to be taken in the U.S. Patent and Trademark Office regarding this application without direct communication between the U.S. attorneys and myself. In the event of a change in the persons from whom instructions may be taken, the U.S. attorneys named herein will be so notified by me.

Send Correspondence to

Direct Telephone Calls to:

WENDEROTH, LIND & PONACK, L.L.P.  
2033 K Street, N.W., Suite 800  
Washington, DC 20006

WENDEROTH, LIND & PONACK, L.L.P.  
Area Code (202) 721-8200

Direct Facsimile Messages to:  
Area Code (202) 721-8250

100 Full Name of First Inventor	FAMILY NAME	FIRST GIVEN NAME	SECOND GIVEN NAME
	TSUKAHARA	Norihito	
Residence & Citizenship	CITY	STATE OR COUNTRY	COUNTRY OF CITIZENSHIP
	Soraku-gun, Kyoto, Japan	JPN	Japan
Post Office Address	ADDRESS	CITY	STATE OR COUNTRY ZIP CODE
	3-403, Esutatakanohara,	2-1-1, Kabutodai, Kizu-cho,	
	Soraku-gun, Kyoto 619-0224 Japan		
200 Full Name of Second Inventor	FAMILY NAME	FIRST GIVEN NAME	SECOND GIVEN NAME
	AKIGUCHI	Takashi	
Residence & Citizenship	CITY	STATE OR COUNTRY	COUNTRY OF CITIZENSHIP
	Osaka-shi, Osaka, Japan	JPN	Japan
Post Office Address	ADDRESS	CITY	STATE OR COUNTRY ZIP CODE
	4-9-23, Yamasaka, Higashisumiyoshi-ku, Osaka-shi,		
	Osaka 546-0035 Japan		
300 Full Name of Third Inventor	FAMILY NAME	FIRST GIVEN NAME	SECOND GIVEN NAME
	MIYAKAWA	Hidenori	
Residence & Citizenship	CITY	STATE OR COUNTRY	COUNTRY OF CITIZENSHIP
	Moriguchi-shi, Osaka, Japan	JPN	Japan
Post Office Address	ADDRESS	CITY	STATE OR COUNTRY ZIP CODE
	1-6-12-303, Jinai-cho, Moriguchi-shi, Osaka		
	570-0056 Japan		
Full Name of Fourth Inventor	FAMILY NAME	FIRST GIVEN NAME	SECOND GIVEN NAME
Residence & Citizenship	CITY	STATE OR COUNTRY	COUNTRY OF CITIZENSHIP
Post Office Address	ADDRESS	CITY	STATE OR COUNTRY ZIP CODE

Full Name of Fifth Inventor	FAMILY NAME	FIRST GIVEN NAME	SECOND GIVEN NAME
Residence & Citizenship	CITY	STATE OR COUNTRY	COUNTRY OF CITIZENSHIP
Post Office Address	ADDRESS	CITY	STATE OR COUNTRY ZIP CODE
Full Name of Sixth Inventor	FAMILY NAME	FIRST GIVEN NAME	SECOND GIVEN NAME
Residence & Citizenship	CITY	STATE OR COUNTRY	COUNTRY OF CITIZENSHIP
Post Office Address	ADDRESS	CITY	STATE OR COUNTRY ZIP CODE
Full Name of Seventh Inventor	FAMILY NAME	FIRST GIVEN NAME	SECOND GIVEN NAME
Residence & Citizenship	CITY	STATE OR COUNTRY	COUNTRY OF CITIZENSHIP
Post Office Address	ADDRESS	CITY	STATE OR COUNTRY ZIP CODE

I further declare that all statements made herein of my own knowledge are true, and that all statements on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

1st Inventor Norihito TSUKAHARA *Norihito Tsukahara* Date 22/11/2001  
 2nd Inventor Takashi AKIGUCHI *Takashi Akiguchi* Date 22/11/2001  
 3rd Inventor Hidenori MIYAKAWA *Hidenori Miyakawa* Date 22/11/2001  
 4th Inventor \_\_\_\_\_ Date \_\_\_\_\_  
 5th Inventor \_\_\_\_\_ Date \_\_\_\_\_  
 6th Inventor \_\_\_\_\_ Date \_\_\_\_\_  
 7th Inventor \_\_\_\_\_ Date \_\_\_\_\_

The above application may be more particularly identified as follows:

U.S. Application Serial No. \_\_\_\_\_ Filing Date \_\_\_\_\_  
 Applicant Reference Number 534653 Atty Docket No. \_\_\_\_\_  
 Title of Invention Semiconductor Device Package Manufacturing Method and  
Semiconductor Device Package Manufactured by the Method